

Yvan Avenas

List of Publications by Year in descending order

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19
papers

867
citations

1040056

9
h-index

888059

17
g-index

19
all docs

19
docs citations

19
times ranked

670
citing authors

#	ARTICLE	IF	CITATIONS
1	Temperature Measurement of Power Semiconductor Devices by Thermo-Sensitive Electrical Parameters—A Review. IEEE Transactions on Power Electronics, 2012, 27, 3081-3092.	7.9	404
2	Improved Reliability of Power Modules: A Review of Online Junction Temperature Measurement Methods. IEEE Industrial Electronics Magazine, 2014, 8, 17-27.	2.6	168
3	Condition Monitoring: A Decade of Proposed Techniques. IEEE Industrial Electronics Magazine, 2015, 9, 22-36.	2.6	78
4	An efficient online time-temperature-dependent creep-fatigue rainflow counting algorithm. International Journal of Fatigue, 2018, 116, 284-292.	5.7	43
5	Preliminary Evaluation of Thermo-Sensitive Electrical Parameters Based on the Forward Voltage for Online Chip Temperature Measurements of IGBT Devices. IEEE Transactions on Industry Applications, 2015, 51, 4688-4698.	4.9	38
6	Effects of Creep Failure Mechanisms on Thermomechanical Reliability of Solder Joints in Power Semiconductors. IEEE Transactions on Power Electronics, 2020, 35, 8956-8964.	7.9	34
7	Parameters affecting forced convection enhancement in ferrofluid cooling systems. Applied Thermal Engineering, 2017, 123, 156-166.	6.0	19
8	Comparison of the electro-thermal constraints on SiC MOSFET and Si IGBT power modules in photovoltaic DC/AC inverters. Microelectronics Reliability, 2017, 78, 65-71.	1.7	17
9	Reliability Assessment of Multistate Degraded Systems: An Application to Power Electronic Systems. IEEE Transactions on Power Electronics, 2020, 35, 4024-4032.	7.9	17
10	Effect of the magnetic field direction on forced convection heat transfer enhancements in ferrofluids. EPJ Applied Physics, 2015, 71, 10901.	0.7	9
11	Reciprocal and Self-Aging Effects of Power Components on Reliability of DC—DC Boost Converter With Coupled and Decoupled Thermal Structures. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 2506-2513.	2.5	7
12	A Method for Accelerated Aging Tests of Power Modules for Photovoltaic Inverters Considering the Inverter Mission Profiles. IEEE Transactions on Power Electronics, 2019, 34, 12226-12234.	7.9	7
13	Thermomechanical Fatigue Damage Model of a Solder Joint in Electronic Devices: An Interval Arithmetic Based Approach. Journal of Electronic Materials, 2022, 51, 5376-5388.	2.2	7
14	Discrete Power Semiconductor Losses Versus Junction Temperature Estimation Based on Thermal Impedance Curves. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2020, 10, 79-87.	2.5	6
15	Numerical and Experimental Evaluation of the Microsecond Pulsed Heating Curve Technique Dedicated to Die Interconnection Characterization. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2016, 6, 835-845.	2.5	4
16	Power Semiconductor Ageing Test Bench Dedicated to Photovoltaic Applications. IEEE Transactions on Industry Applications, 2019, 55, 3003-3010.	4.9	4
17	Power semiconductor ageing test bench dedicated to photovoltaic applications. , 2018, , .		3
18	Realization and characterization of instrumented power diode with aluminum RTD sensor — application to thermal impedance evaluation. EPE Journal (European Power Electronics and Drives) Tj ETQq0 0 0 rgBT/Overlock 10 Tf 00		

#	ARTICLE	IF	CITATIONS
19	Implementation of TAPIR Switching Cells with Integrated Direct Air-Cooling for SiC Power Devices. , 2020, , .		1